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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	20
Program Memory Size	3KB (2K x 12)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	72 x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c57c-20i-so

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

TABLE 1-1: PIC16C5X FAMILY OF DEVICES

Features	PIC16C54	PIC16CR54	PIC16C55	PIC16C56	PIC16CR56
Maximum Operation Frequency	40 MHz	20 MHz	40 MHz	40 MHz	20 MHz
EPROM Program Memory (x12 words)	512	_	512	1K	
ROM Program Memory (x12 words)		512	_	_	1K
RAM Data Memory (bytes)	25	25	24	25	25
Timer Module(s)	TMR0	TMR0	TMR0	TMR0	TMR0
I/O Pins	12	12	20	12	12
Number of Instructions	33	33	33	33	33
Packages	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP	28-pin DIP, SOIC; 28-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP

PIC16C58 Features **PIC16C57** PIC16CR57 PIC16CR58 Maximum Operation Frequency 20 MHz 40 MHz 40 MHz 20 MHz EPROM Program Memory (x12 words) 2K 2K ____ _ ROM Program Memory (x12 words) 2K 2K _ _ RAM Data Memory (bytes) 72 72 73 73 Timer Module(s) TMR0 TMR0 TMR0 TMR0 I/O Pins 20 20 12 12 Number of Instructions 33 33 33 33 28-pin DIP, SOIC; 28-pin DIP, SOIC; 18-pin DIP, SOIC; 18-pin DIP, SOIC; Packages 28-pin SSOP 28-pin SSOP 20-pin SSOP 20-pin SSOP All PIC® Family devices have Power-on Reset, selectable Watchdog Timer, selectable Code Protect and high I/O current capability.

6.4 **OPTION Register**

The OPTION Register is a 6-bit wide, write-only register which contains various control bits to configure the Timer0/WDT prescaler and Timer0.

By executing the OPTION instruction, the contents of the W Register will be transferred to the OPTION Register. A RESET sets the OPTION<5:0> bits.

REGISTER 6-2: OPTION REGISTER

U-0	U-0	W-1	W-1	W-1	W-1	W-1	W-1
_	_	TOCS	TOSE	PSA	PS2	PS1	PS0
bit 7							bit 0

- bit 7-6: Unimplemented: Read as '0'
- bit 5: **TOCS**: Timer0 clock source select bit
 - 1 = Transition on T0CKI pin
 - 0 = Internal instruction cycle clock (CLKOUT)
- bit 4: **TOSE**: Timer0 source edge select bit
 - 1 = Increment on high-to-low transition on T0CKI pin
 - 0 = Increment on low-to-high transition on T0CKI pin
- bit 3: **PSA**: Prescaler assignment bit
 - 1 = Prescaler assigned to the WDT
 - 0 = Prescaler assigned to Timer0

bit 2-0: **PS<2:0>:** Prescaler rate select bits

Bit Value	Timer0 Rate	WDT Rate
000	1:2	1:1
001	1:4	1:2
010	1:8	1:4
011	1:16	1:8
100	1:32	1:16
101	1:64	1:32
110	1:128	1:64
111	1:256	1:128

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented b	it, read as '0'
-n = Value at POR	1 = bit is set	0 = bit is cleared	x = bit is unknown

NOTES:

7.6 I/O Programming Considerations

7.6.1 BI-DIRECTIONAL I/O PORTS

Some instructions operate internally as read followed by write operations. The BCF and BSF instructions, for example, read the entire port into the CPU, execute the bit operation and re-write the result. Caution must be used when these instructions are applied to a port where one or more pins are used as input/outputs. For example, a BSF operation on bit5 of PORTB will cause all eight bits of PORTB to be read into the CPU, bit5 to be set and the PORTB value to be written to the output latches. If another bit of PORTB is used as a bi-directional I/O pin (say bit0) and it is defined as an input at this time, the input signal present on the pin itself would be read into the CPU and rewritten to the data latch of this particular pin, overwriting the previous content. As long as the pin stays in the Input mode, no problem occurs. However, if bit0 is switched into Output mode later on, the content of the data latch may now be unknown.

Example 7-1 shows the effect of two sequential read-modify-write instructions (e.g., BCF, BSF, etc.) on an I/O port.

A pin actively outputting a high or a low should not be driven from external devices at the same time in order to change the level on this pin ("wired-or", "wired-and"). The resulting high output currents may damage the chip.

EXAMPLE 7-1: READ-MODIFY-WRITE INSTRUCTIONS ON AN I/O PORT

;Initial PORT Settings
; PORTB<7:4> Inputs
; PORTB<3:0> Outputs
;PORTB<7:6> have external pull-ups and are
;not connected to other circuitry
;

;				PORT	latch	PORT	pins
;							
	BCF	PORTB,	7	;01pp	pppp	11pp	pppp
	BCF	PORTB,	6	;10pp	pppp	11pp	pppp
	MOVLW	H'3F'		;			
	TRIS	PORTB		;10pp	pppp	10pp	pppp
;							

;Note that the user may have expected the pin ;values to be 00pp pppp. The 2nd BCF caused ;RB7 to be latched as the pin value (High).

7.6.2 SUCCESSIVE OPERATIONS ON I/O PORTS

The actual write to an I/O port happens at the end of an instruction cycle, whereas for reading, the data must be valid at the beginning of the instruction cycle (Figure 7-2). Therefore, care must be exercised if a write followed by a read operation is carried out on the same I/O port. The sequence of instructions should allow the pin voltage to stabilize (load dependent) before the next instruction, which causes that file to be read into the CPU, is executed. Otherwise, the previous state of that pin may be read into the CPU rather than the new state. When in doubt, it is better to separate these instructions with a NOP or another instruction not accessing this I/O port.

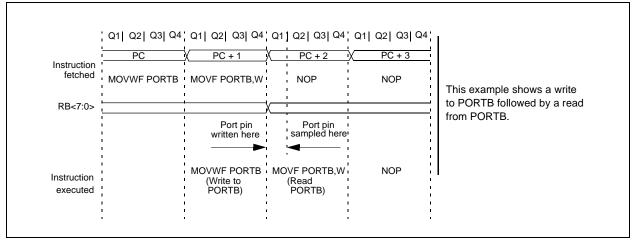


FIGURE 7-2: SUCCESSIVE I/O OPERATION

9.1 Configuration Bits

Configuration bits can be programmed to select various device configurations. Two bits are for the selection of the oscillator type and one bit is the Watchdog Timer enable bit. Nine bits are code protection bits for the PIC16C54A, PIC16CR54A, PIC16C55A, PIC16C56A, PIC16CR56A, PIC16CR57C, PIC16CR57C, PIC16CR57C,

PIC16C58B, and PIC16CR58B devices (Register 9-1). One bit is for code protection for the PIC16C54, PIC16C55, PIC16C56 and PIC16C57 devices (Register 9-2).

QTP or ROM devices have the oscillator configuration programmed at the factory and these parts are tested accordingly (see "Product Identification System" diagrams in the back of this data sheet).

REGISTER 9-1: CONFIGURATION WORD FOR PIC16C54A/CR54A/C54C/CR54C/C55A/C56A/ CR56A/C57C/CR57C/C58B/CR58B

CP	CP	CP	CP	CP	CP	CP	CP	CP	WDTE	FOSC1	FOSC0
bit 11											bit 0

bit 11-3: CP: Code Protection Bit

- 1 = Code protection off
 - 0 =Code protection on
- bit 2: WDTE: Watchdog timer enable bit
 - 1 = WDT enabled
 - 0 = WDT disabled

bit 1-0: FOSC1:FOSC0: Oscillator Selection Bit

- 00 = LP oscillator
- 01 = XT oscillator
- 10 = HS oscillator
- 11 = RC oscillator

Note 1: Refer to the PIC16C5X Programming Specification (Literature Number DS30190) to determine how to access the configuration word.

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, re	ead as '0'
-n = Value at POR	1 = bit is set	0 = bit is cleared	x = bit is unknown

11.8 MPLAB ICD In-Circuit Debugger

Microchip's In-Circuit Debugger, MPLAB ICD, is a powerful, low cost, run-time development tool. This tool is based on the FLASH PIC MCUs and can be used to develop for this and other PIC microcontrollers. The MPLAB ICD utilizes the in-circuit debugging capability built into the FLASH devices. This feature, along with Microchip's In-Circuit Serial ProgrammingTM protocol, offers cost-effective in-circuit FLASH debugging from the graphical user interface of the MPLAB Integrated Development Environment. This enables a designer to develop and debug source code by watching variables, single-stepping and setting break points. Running at full speed enables testing hardware in real-time.

11.9 PRO MATE II Universal Device Programmer

The PRO MATE II universal device programmer is a full-featured programmer, capable of operating in Stand-alone mode, as well as PC-hosted mode. The PRO MATE II device programmer is CE compliant.

The PRO MATE II device programmer has programmable VDD and VPP supplies, which allow it to verify programmed memory at VDD min and VDD max for maximum reliability. It has an LCD display for instructions and error messages, keys to enter commands and a modular detachable socket assembly to support various package types. In Stand-alone mode, the PRO MATE II device programmer can read, verify, or program PIC devices. It can also set code protection in this mode.

11.10 PICSTART Plus Entry Level Development Programmer

The PICSTART Plus development programmer is an easy-to-use, low cost, prototype programmer. It connects to the PC via a COM (RS-232) port. MPLAB Integrated Development Environment software makes using the programmer simple and efficient.

The PICSTART Plus development programmer supports all PIC devices with up to 40 pins. Larger pin count devices, such as the PIC16C92X and PIC17C76X, may be supported with an adapter socket. The PICSTART Plus development programmer is CE compliant.

11.11 PICDEM 1 Low Cost PIC MCU Demonstration Board

The PICDEM 1 demonstration board is a simple board which demonstrates the capabilities of several of Microchip's microcontrollers. The microcontrollers supported are: PIC16C5X (PIC16C54 to PIC16C58A). PIC16C61, PIC16C62X, PIC16C71, PIC16C8X, PIC17C42, PIC17C43 and PIC17C44. All necessary hardware and software is included to run basic demo programs. The user can program the sample microcontrollers provided with the PICDEM 1 demonstration board on a PRO MATE II device programmer, or a PICSTART Plus development programmer, and easily test firmware. The user can also connect the PICDEM 1 demonstration board to the MPLAB ICE incircuit emulator and download the firmware to the emulator for testing. A prototype area is available for the user to build some additional hardware and connect it to the microcontroller socket(s). Some of the features include an RS-232 interface, a potentiometer for simulated analog input, push button switches and eight LEDs connected to PORTB.

11.12 PICDEM 2 Low Cost PIC16CXX Demonstration Board

The PICDEM 2 demonstration board is a simple demonstration board that supports the PIC16C62, PIC16C64, PIC16C65, PIC16C73 and PIC16C74 microcontrollers. All the necessary hardware and software is included to run the basic demonstration programs. The user can program the sample microcontrollers provided with the PICDEM 2 demonstration board on a PRO MATE II device programmer, or a PICSTART Plus development programmer, and easily test firmware. The MPLAB ICE in-circuit emulator may also be used with the PICDEM 2 demonstration board to test firmware. A prototype area has been provided to the user for adding additional hardware and connecting it to the microcontroller socket(s). Some of the features include a RS-232 interface, push button switches, a potentiometer for simulated analog input, a serial EEPROM to demonstrate usage of the I^2C^{TM} bus and separate headers for connection to an LCD module and a keypad.

11.13 PICDEM 3 Low Cost PIC16CXXX Demonstration Board

The PICDEM 3 demonstration board is a simple demonstration board that supports the PIC16C923 and PIC16C924 in the PLCC package. It will also support future 44-pin PLCC microcontrollers with an LCD Module. All the necessary hardware and software is included to run the basic demonstration programs. The user can program the sample microcontrollers provided with the PICDEM 3 demonstration board on a PRO MATE II device programmer, or a PICSTART Plus development programmer with an adapter socket, and easily test firmware. The MPLAB ICE in-circuit emulator may also be used with the PICDEM 3 demonstration board to test firmware. A prototype area has been provided to the user for adding hardware and connecting it to the microcontroller socket(s). Some of the features include a RS-232 interface, push button switches, a potentiometer for simulated analog input, a thermistor and separate headers for connection to an external LCD module and a keypad. Also provided on the PICDEM 3 demonstration board is a LCD panel, with 4 commons and 12 segments, that is capable of displaying time, temperature and day of the week. The PICDEM 3 demonstration board provides an additional RS-232 interface and Windows software for showing the demultiplexed LCD signals on a PC. A simple serial interface allows the user to construct a hardware demultiplexer for the LCD signals.

11.14 PICDEM 17 Demonstration Board

The PICDEM 17 demonstration board is an evaluation board that demonstrates the capabilities of several Microchip microcontrollers, including PIC17C752, PIC17C756A, PIC17C762 and PIC17C766. All necessary hardware is included to run basic demo programs, which are supplied on a 3.5-inch disk. A programmed sample is included and the user may erase it and program it with the other sample programs using the PRO MATE II device programmer, or the PICSTART Plus development programmer, and easily debug and test the sample code. In addition, the PICDEM 17 demonstration board supports downloading of programs to and executing out of external FLASH memory on board. The PICDEM 17 demonstration board is also usable with the MPLAB ICE in-circuit emulator, or the PICMASTER emulator and all of the sample programs can be run and modified using either emulator. Additionally, a generous prototype area is available for user hardware.

11.15 KEELOQ Evaluation and Programming Tools

KEELOQ evaluation and programming tools support Microchip's HCS Secure Data Products. The HCS evaluation kit includes a LCD display to show changing codes, a decoder to decode transmissions and a programming interface to program test transmitters.

13.2 DC Characteristics: PIC16CR54A-04E, 10E, 20E (Extended)

PIC16CR54A-04E, 10E, 20E (Extended)			Standard Operating Conditions (unless otherwise specifOperating Temperature $-40^{\circ}C \le TA \le +125^{\circ}C$ for extended				
Param No.	Symbol	Characteristic	Min	Тур†	Max	Units	Conditions
D001	Vdd	Supply Voltage RC, XT and LP modes HS mode	3.25 4.5		6.0 5.5	V V	
D002	Vdr	RAM Data Retention Voltage ⁽¹⁾	—	1.5*	—	V	Device in SLEEP mode
D003	VPOR	VDD Start Voltage to ensure Power-on Reset	—	Vss	—	V	See Section 5.1 for details on Power-on Reset
D004	Svdd	VDD Rise Rate to ensure Power- on Reset	0.05*	_		V/ms	See Section 5.1 for details on Power-on Reset
D010	IDD	Supply Current ⁽²⁾ RC ⁽³⁾ and XT modes HS mode HS mode		1.8 4.8 9.0	3.3 10 20	mA mA mA	Fosc = 4.0 MHz, Vdd = 5.5V Fosc = 10 MHz, Vdd = 5.5V Fosc = 16 MHz, Vdd = 5.5V
D020	IPD	Power-down Current ⁽²⁾		5.0 0.8	22 18	μΑ μΑ	VDD = 3.25V, WDT enabled VDD = 3.25V, WDT disabled

These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

- 2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.
 - a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to Vss, TOCKI = VDD, MCLR = VDD; WDT enabled/ disabled as specified.
 - b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.
- 3: Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in kΩ.

PIC16C5X

FIGURE 14-2: TYPICAL RC OSC FREQUENCY vs. VDD, CEXT = 20 PF Typical: statistical mean @ 25°C Maximum: mean + 3s (-40°C to 125°C) Minimum: mean – 3s (-40°C to 125°C) 5.5 R = 3.3K5.0 4.5 R = 5K 4.0 3.5 Fosc (MHz) 3.0 R = 10K 2.5 2.0 Measured on DIP Packages, $T = 25^{\circ}C$ 1.5 1.0 R = 100K 0.5 0.0 3.0 3.5 4.0 4.5 5.0 5.5 6.0 VDD (Volts)

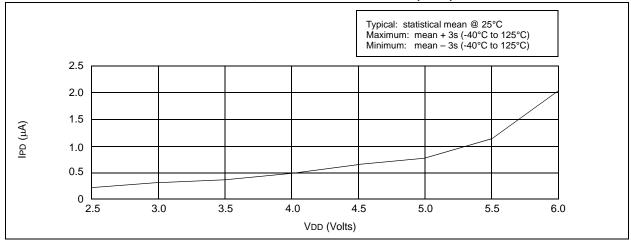
FIGURE 14-3:

TYPICAL RC OSC FREQUENCY vs. VDD, CEXT = 100 PF



PIC16C5X

FIGURE 16-5: TYPICAL IPD vs. VDD, WATCHDOG DISABLED (25°C)







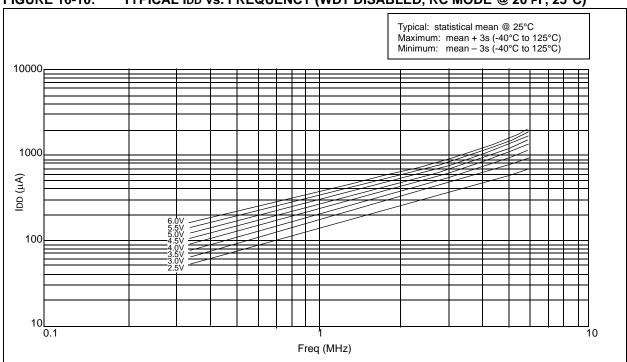
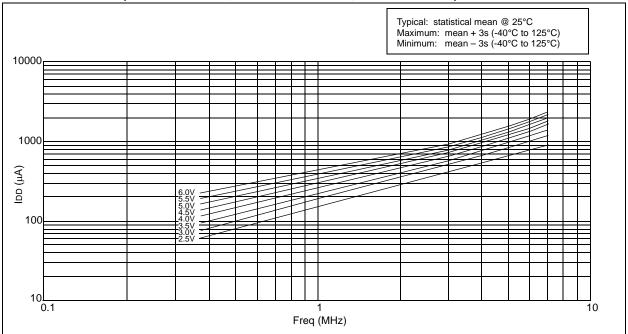


FIGURE 16-10: TYPICAL IDD vs. FREQUENCY (WDT DISABLED, RC MODE @ 20 PF, 25°C)

FIGURE 16-11: MAXIMUM IDD vs. FREQUENCY (WDT DISABLED, RC MODE @ 20 PF, -40°C to +85°C)



NOTES:

17.1 DC Characteristics:PIC16C54C/C55A/C56A/C57C/C58B-04, 20 (Commercial, Industrial) PIC16LC54C/LC55A/LC56A/LC57C/LC58B-04 (Commercial, Industrial) PIC16CR54C/CR56A/CR57C/CR58B-04, 20 (Commercial, Industrial) PIC16LCR54C/LCR56A/LCR57C/LCR58B-04 (Commercial, Industrial)

PIC16LC PIC16LC (Comm	CR5XOperating Temperature $0^{\circ}C \le TA \le +70^{\circ}C$ for commercian					ions (unless otherwise specified) $0^{\circ}C \le TA \le +70^{\circ}C$ for commercial $-40^{\circ}C \le TA \le +85^{\circ}C$ for industrial	
PIC16C5 PIC16CF (Comm		ustrial)				ions (unless otherwise specified) $0^{\circ}C \le TA \le +70^{\circ}C$ for commercial $-40^{\circ}C \le TA \le +85^{\circ}C$ for industrial	
Param No.	Symbol	Characteristic/Device	Min	Min Typ† Max Units Conditions			
	IDD	Supply Current ^(2,3)					
D010		PIC16LC5X		0.5	2.4	mA	Fosc = 4.0 MHz, VDD = 5.5V, XT and
			—	11	27	μA	RC modes
							FOSC = 32 kHz, VDD = 2.5 V, LP mode,
			_	14	35	μA	Commercial Fosc = 32 kHz, VDD = 2.5V, LP mode,
							Industrial
D010A		PIC16C5X	_	1.8	2.4	mA	FOSC = 4 MHz, VDD = 5.5V, XT and RC
				2.6 4.5	3.6* 16	mA mA	modes Fosc = 10 MHz, VDD = 3.0V, HS mode
				4.5	32	μA	FOSC = 20 MHz, VDD = 3.00, HS mode FOSC = 20 MHz, VDD = 5.5V, HS mode
				14	52	μΛ	FOSC = 32 kHz, VDD = 3.3 V, HS mode
			_	17	40	μA	Commercial
							Fosc = 32 kHz, VDD = 3.0V, LP mode, Industrial

Legend: Rows with standard voltage device data only are shaded for improved readability.

* These parameters are characterized but not tested.

- † Data in "Typ" column is at 5V, 25°C, unless otherwise stated. These parameters are for design guidance only, and are not tested.
- Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.
 - 2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.
 - a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to VSS, T0CKI = VDD, MCLR = VDD; WDT enabled/disabled as specified.
 - b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.
 - 3: Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in k Ω .

PIC16C5X

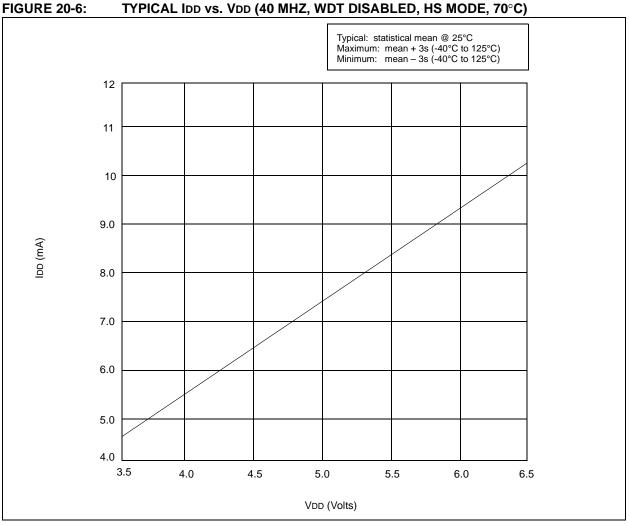




TABLE 20-1: INPUT CAPACITANCE

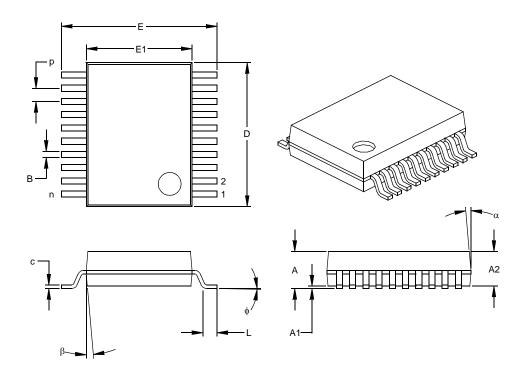
Pin	Typical Capa	acitance (pF)
FIII	18L PDIP	18L SOIC
RA port	5.0	4.3
RB port	5.0	4.3
MCLR	17.0	17.0
OSC1	4.0	3.5
OSC2/CLKOUT	4.3	3.5
тоскі	3.2	2.8

All capacitance values are typical at 25° C. A part-to-part variation of ±25% (three standard deviations) should be taken into account.



20-Lead Plastic Shrink Small Outline (SS) - 209 mil, 5.30 mm (SSOP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units		INCHES*		MILLIMETERS			
Dimensio	MIN	NOM	MAX	MIN	NOM	MAX		
Number of Pins	n		20			20		
Pitch	р		.026			0.65		
Overall Height	Α	.068	.073	.078	1.73	1.85	1.98	
Molded Package Thickness	A2	.064	.068	.072	1.63	1.73	1.83	
Standoff §	A1	.002	.006	.010	0.05	0.15	0.25	
Overall Width	Е	.299	.309	.322	7.59	7.85	8.18	
Molded Package Width	E1	.201	.207	.212	5.11	5.25	5.38	
Overall Length	D	.278	.284	.289	7.06	7.20	7.34	
Foot Length	L	.022	.030	.037	0.56	0.75	0.94	
Lead Thickness	С	.004	.007	.010	0.10	0.18	0.25	
Foot Angle	ф	0	4	8	0.00	101.60	203.20	
Lead Width	В	.010	.013	.015	0.25	0.32	0.38	
Mold Draft Angle Top	α	0	5	10	0	5	10	
Mold Draft Angle Bottom	β	0	5	10	0	5	10	

* Controlling Parameter

§ Significant Characteristic

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side. JEDEC Equivalent: MO-150 Drawing No. C04-072

28-Lead Ceramic Dual In-line with Window (JW) - 600 mil (CERDIP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units	Units INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		28			28	
Pitch	р		.100			2.54	
Top to Seating Plane	Α	.195	.210	.225	4.95	5.33	5.72
Ceramic Package Height	A2	.155	.160	.165	3.94	4.06	4.19
Standoff	A1	.015	.038	.060	0.38	0.95	1.52
Shoulder to Shoulder Width	Е	.595	.600	.625	15.11	15.24	15.88
Ceramic Pkg. Width	E1	.514	.520	.526	13.06	13.21	13.36
Overall Length	D	1.430	1.460	1.490	36.32	37.08	37.85
Tip to Seating Plane	L	.125	.138	.150	3.18	3.49	3.81
Lead Thickness	С	.008	.010	.012	0.20	0.25	0.30
Upper Lead Width	B1	.050	.058	.065	1.27	1.46	1.65
Lower Lead Width	В	.016	.020	.023	0.41	0.51	0.58
Overall Row Spacing §	eB	.610	.660	.710	15.49	16.76	18.03
Window Diameter	W	.270	.280	.290	6.86	7.11	7.37

Sontolling Parameter
 Significant Characteristic
 JEDEC Equivalent: MO-103
 Drawing No. C04-013

w

W Register	
Value on reset	20
Wake-up from SLEEP	19, 47
Watchdog Timer (WDT)	43, 46
Period	
Programming Considerations	
Register values on reset	
WWW, On-Line Support	
X	
XORLW	60
XORWF	
Z	
Zero (Z) bit	9, 29

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